

IN THE CLAIMS:

Please cancel claims 3, 11 and 19 without prejudice or disclaimer and amend the remaining claims as follows.

1. (currently amended) An apparatus, comprising:
 - a thermally conductive core;
 - a thermally conductive frame positioned around the core, the frame defining at least one opening; and
 - at least one thermally conductive insert disposed in the opening in the frame,
wherein the core includes a post and base, with the base protruding from the frame.
2. (original) The apparatus of claim 1, wherein the frame defines an opening adapted to receive the core and the core is disposed inside the opening adapted to receive the core.
3. (canceled).
4. (original) The apparatus of claim 1, wherein the core and frame are monolithic.
5. (currently amended) ~~The~~ An apparatus of claim 1, comprising:
 - a thermally conductive core;
 - a thermally conductive frame positioned around the core, wherein the frame includes a framework of members defining an array of openings; and
 - with the a plurality of thermally conductive inserts respectively disposed in the openings in the frame.

6. (original) The apparatus of claim 5, wherein the framework includes a primary member and a secondary member, wherein the primary member is thicker than the secondary member.

7. (currently amended) ~~The An~~ apparatus of claim 1, comprising:
a thermally conductive core;
a thermally conductive frame positioned around the core, the frame
defining at least one opening; and
at least one thermally conductive insert disposed in the opening in
the frame,

wherein the ~~inserts~~ include at least one insert includes at least one insert having a folded fin structure.

8. (currently amended) The apparatus of claim 4 7, wherein:
the core comprises a copper post; and
the frame comprises extruded aluminum; and
~~the inserts comprise folded fin structures.~~

9. (currently amended) A method, comprising:
providing a thermally conductive core;
positioning a thermally conductive frame around the core, the frame
defining at least one opening; and
inserting a thermally conductive insert in the opening in the frame,
wherein the core includes a post and base, with the base protruding
from the frame.

10. (original) The method of claim 9, wherein the frame defines an opening adapted to receive the core and the positioning comprises securing the core inside the opening adapted to receive the core.

11. (canceled).

12. (original) The method of claim 9, wherein the core and frame are monolithic.
13. (currently amended) ~~The A method of claim 9, comprising:~~
~~providing a thermally conductive core;~~
~~positioning a thermally conductive frame around the core, wherein~~
the frame includes a framework of members defining an array of openings; and
~~the inserting comprises inserting a plurality of thermally conductive~~
inserts in respective openings of the array of openings.
14. (original) The method of claim 13, wherein the framework includes a primary member and a secondary member, wherein the primary member is thicker than the secondary member.
15. (currently amended) ~~The A method of claim 9, comprising:~~
~~providing a thermally conductive core;~~
~~positioning a thermally conductive frame around the core, the frame~~
defining at least one opening; and
inserting a thermally conductive insert in the opening in the frame,
~~wherein the inserts include at least one insert includes an insert~~
having a folded fin structure.
16. (currently amended) The method of claim 9 15, wherein:
the core comprises a copper post;
the frame comprises extruded aluminum; and
~~the insert comprise a folded fin structure.~~

17. (currently amended) A system, comprising:
 - a heatsink assembly, comprising:
 - a thermally conductive core;
 - a thermally conductive frame positioned around the core, the frame defining at least one opening, wherein the core includes a post and base, with the base protruding from the frame;
 - at least one thermally conductive insert disposed in the opening in the frame; and
 - an electronic component thermally coupled to the core of the heatsink.
18. (original) The system of claim 17, wherein the frame defines an opening adapted to receive the core and the core is disposed inside the opening adapted to receive the core.
19. (canceled).
20. (currently amended) The system of claim 19 17, wherein the electronic component is thermally coupled to the protruding base of the core, providing an air gap between the electronic component and the heatsink.
21. (currently amended) The system of claim 21 17, furthering further comprising a fan mounted to the heatsink and configured to draw air through the heatsink outward from the electronic component.
22. (original) The system of claim 17, wherein the core and frame are monolithic.

23. (currently amended) ~~The A system of claim 17, comprising:~~
a heatsink assembly, comprising:
a thermally conductive core;
a thermally conductive frame positioned around the core,

wherein the frame includes a framework of members defining an array of openings;

with the a plurality of thermally conductive inserts
respectively disposed in the openings in the frame; and
an electronic component thermally coupled to the core of the
heatsink.

24. (original) The system of claim 23, wherein the framework includes a primary member and a secondary member, wherein the primary member is thicker than the secondary member.

25. (currently amended) ~~The A system of claim 17, comprising:~~
a heatsink assembly, comprising:
a thermally conductive core;
a thermally conductive frame positioned around the core, the
frame defining at least one opening;
at least one thermally conductive insert disposed in the
opening in the frame; and
an electronic component thermally coupled to the core of the
heatsink,
wherein the ~~inserts include~~ at least one insert includes at least one insert having a folded fin structure.

26. (currently amended) The system of claim 17 25, wherein:
the core comprises a copper post;
the frame comprises extruded aluminum; and
~~the inserts comprise folded fin structures.~~
27. (currently amended) ~~The A system of claim 17, further comprising:~~
a heatsink assembly, comprising:
a thermally conductive core;
a thermally conductive frame positioned around the core, the
frame defining at least one opening;
at least one thermally conductive insert disposed in the
opening in the frame;
an electronic component thermally coupled to the core of the
heatsink; and
a fan mounted to the heatsink.
28. (original) The system of claim 27, further comprising:
a system board, with the electronic component mounted on the
system board.
29. (original) The system of claim 28, further comprising:
a circuit card connected to the system board.
30. (original) The system of claim 28, wherein the system board
comprises a motherboard and the electronic component comprises a
microprocessor.
31. (original) The system of claim 28, further comprising:
a display operably connected to the system board.